

# GSM1362TF

## 100V N-Channel MOSFET

### Product Description

The N-Channel enhancement mode power field effect transistor is using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

The device is well suited for high efficiency fast switching applications.

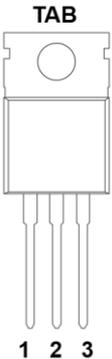
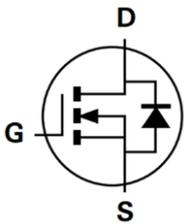
### Features

- $R_{DS(ON)} = 6.4m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} = 9.6m\Omega @ V_{GS}=4.5V$
- TO-220-3L Package
- RoHS Compliant and Halogen Free

### Applications

- MB / VGA / Vcore
- POL Applications
- SMPS

### Packages & Pin Assignments

TO-220-3L			Equivalent Circuit		
					
Pin	Symbol	Description	Pin	Symbol	Description
1	G	Gate	2	D	Drain
3	S	Source	TAB	D	Drain

## Ordering and Marking Information

Ordering Information			
Part Number	Package	Part Marking	Quantity / Tube
GSM1362TF	TO-220-3L	1362TF □□□□□□	50 PCS
<b>GSM1362</b> <span style="border: 1px solid black; padding: 0 2px;">1</span> <span style="border: 1px solid black; padding: 0 2px;">2</span>			
- <b>Product Code:</b> GSM1362		- <b>Package Code:</b> <span style="border: 1px solid black; padding: 0 2px;">1</span> is T for TO-220-3L	
- <b>Green Level:</b> <span style="border: 1px solid black; padding: 0 2px;">2</span> is F for RoHS Compliant and Halogen Free			
Marking Information			
		- <b>Product Code:</b> 1362TF	
		- <b>GS Code:</b> □□□□□□	

## Absolute Maximum Ratings (T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Value	Unit	
V <sub>DSS</sub>	Drain-Source Voltage	100	V	
V <sub>GSS</sub>	Gate-Source Voltage	±20	V	
I <sub>D</sub>	Continuous Drain Current (Silicon Limited)	T <sub>C</sub> =25°C	110	A
		T <sub>C</sub> =100°C	68	
	Continuous Drain Current (Package Limited)		100	
I <sub>DM</sub>	Pulsed Drain Current <sup>1</sup>	245	A	
I <sub>AS</sub>	Single Pulse Avalanche Current, L = 0.1mH <sup>1</sup>	25	A	
E <sub>AS</sub>	Single Pulse Avalanche Energy, L = 0.1mH <sup>1</sup>	62.5	mJ	
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> =25°C	156	W
		T <sub>C</sub> =100°C	62.5	
R <sub>θJC</sub>	Thermal Resistance-Junction to Case	0.8	°C/W	
R <sub>θJA</sub>	Thermal Resistance-Junction to Ambient <sup>2</sup>	62	°C/W	
T <sub>J</sub>	Operating Junction Temperature Range	-55 to +150	°C	
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C	

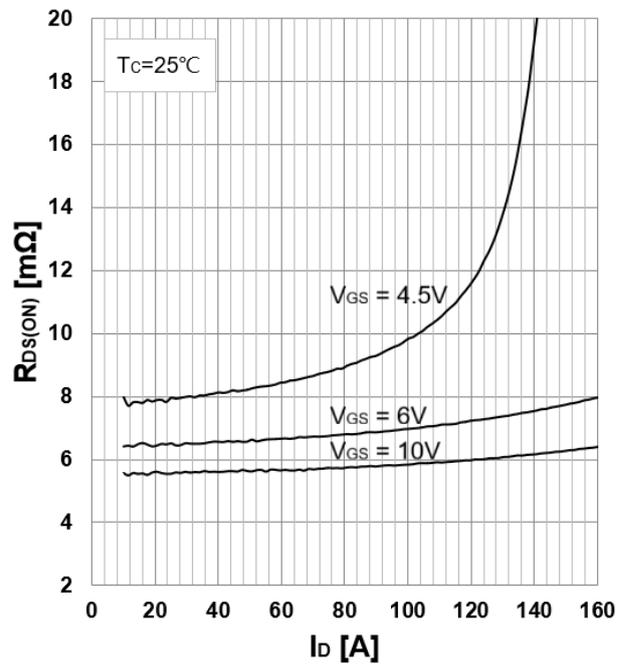
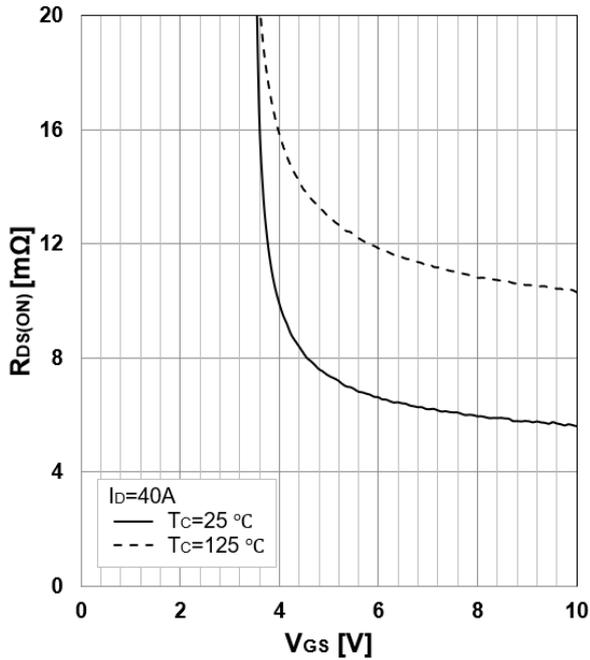
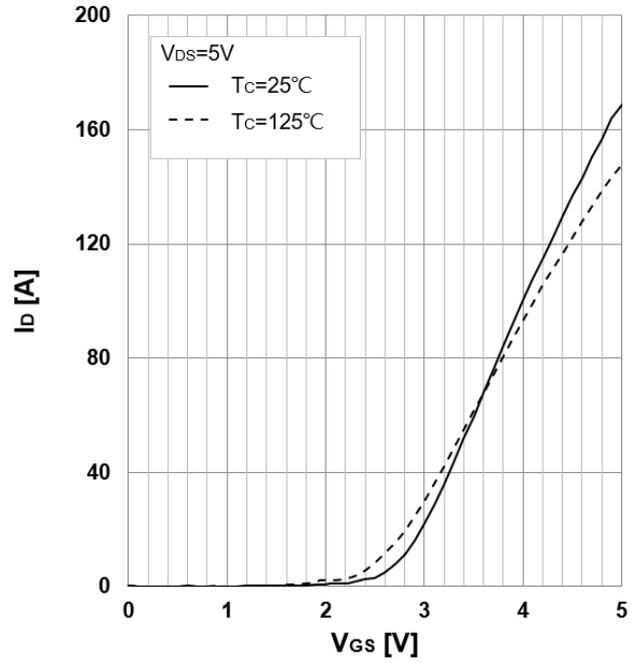
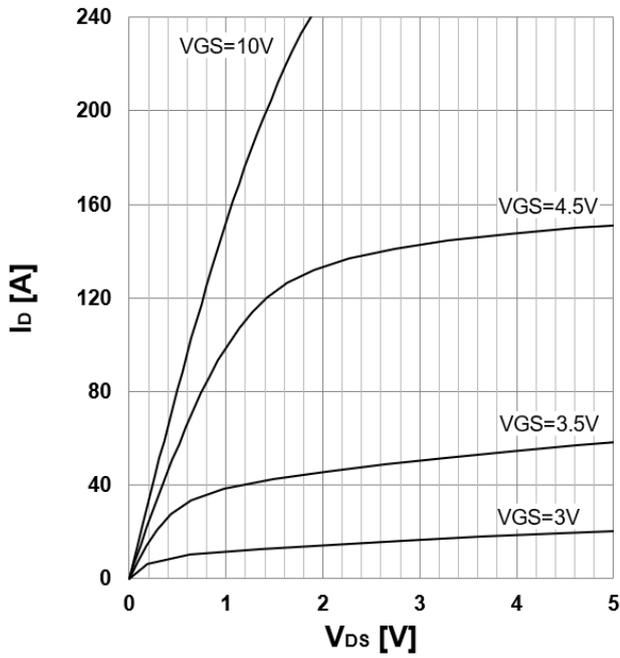
**NOTE:**

1. Single pulse width is limited by max junction temperature.

## Electrical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
B <sub>V</sub> DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	-	-	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V	-	-	1	μA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	-	-	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	-	2.5	V
R <sub>DS(ON)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =40A	-	5.6	6.4	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	8	9.6	
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =30A	-	42	-	S
<b>Dynamic Characteristics</b>						
R <sub>g</sub>	Gate Resistance	f=1MHz		0.8		Ω
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=1MHz	-	2340	-	pF
C <sub>oss</sub>	Output Capacitance		-	455	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	22	-	
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =50V, I <sub>D</sub> =40A V <sub>GS</sub> =10V	-	54	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	8	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	20	-	
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =50V, I <sub>D</sub> =40A V <sub>GS</sub> =10V, R <sub>g</sub> =3Ω	-	20	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	10	-	
t <sub>d(off)</sub>	Turn-Off Delay Time		-	31	-	
t <sub>f</sub>	Turn-Off Fall Time		-	7	-	
<b>Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A	-	-	1	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>R</sub> =50V, I <sub>F</sub> =40A , di/dt=100A/μs	-	58	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	115	-	nC

## Typical Performance Characteristics



## Typical Performance Characteristics

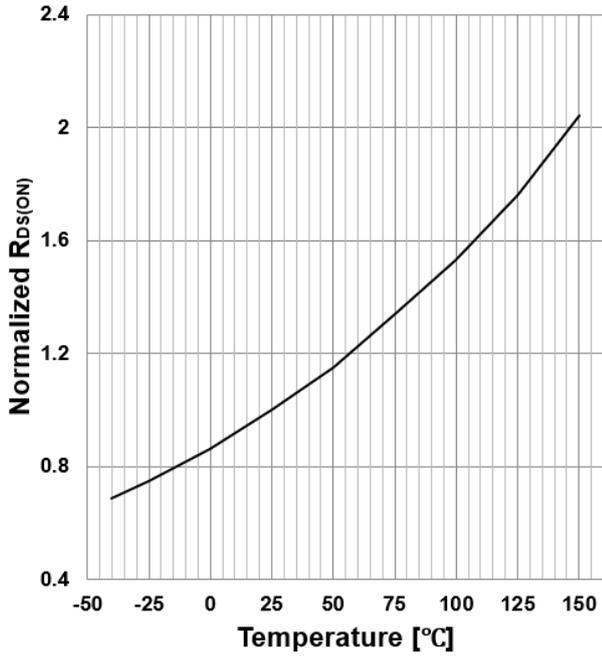


FIG.5 Normalized On-Resistance vs.  $T_J$

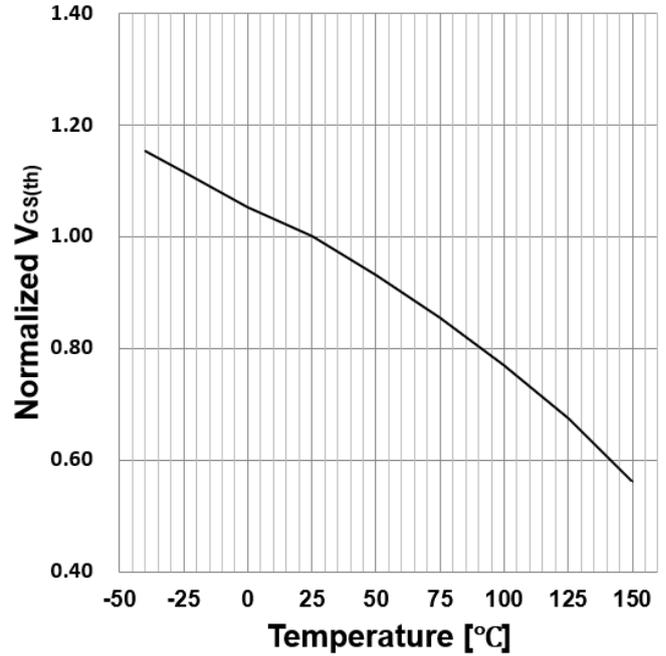


FIG.6 Normalized  $V_{GS(th)}$  vs.  $T_J$

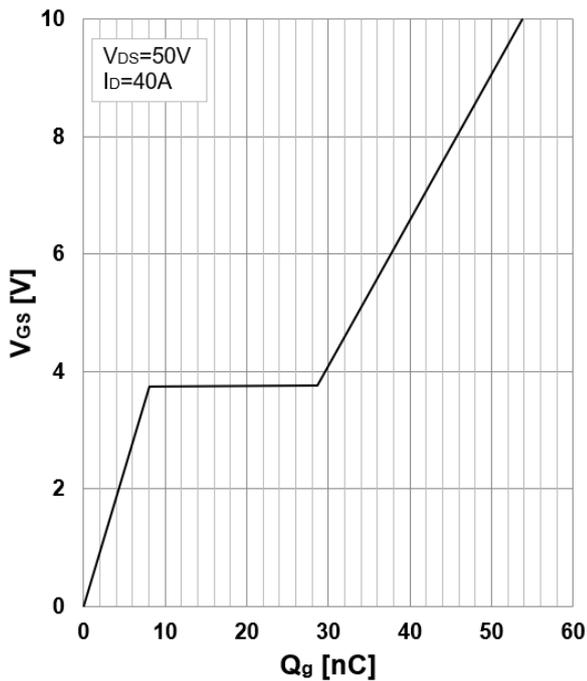


FIG.7 Gate Charge Characteristics

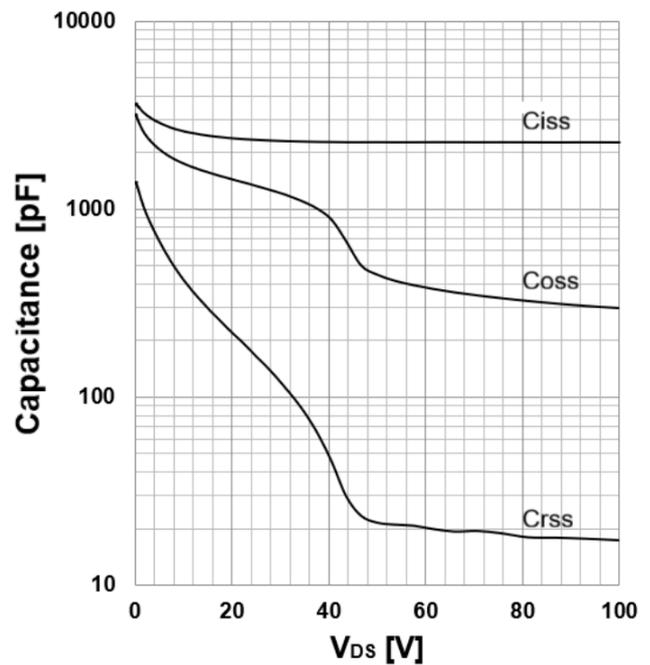


FIG.8 Capacitance Characteristics

## Typical Performance Characteristics

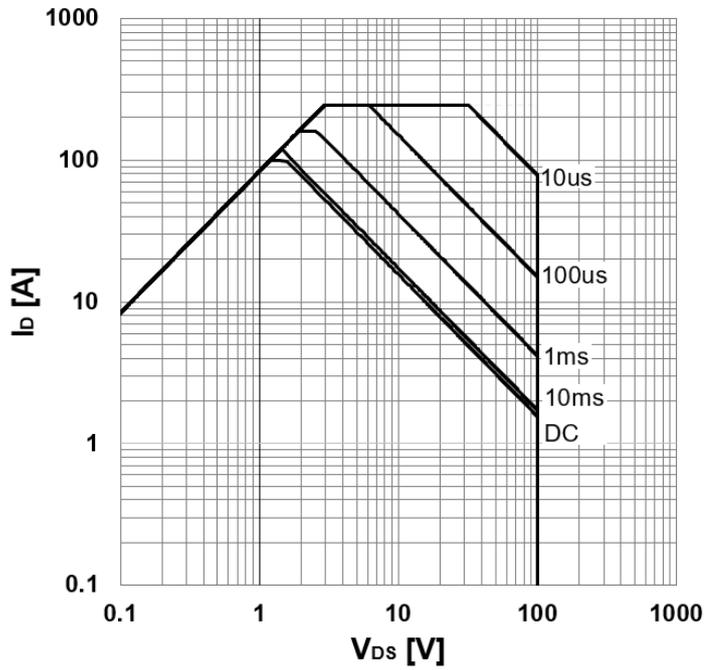


FIG.9 Maximum Safe Operation Area

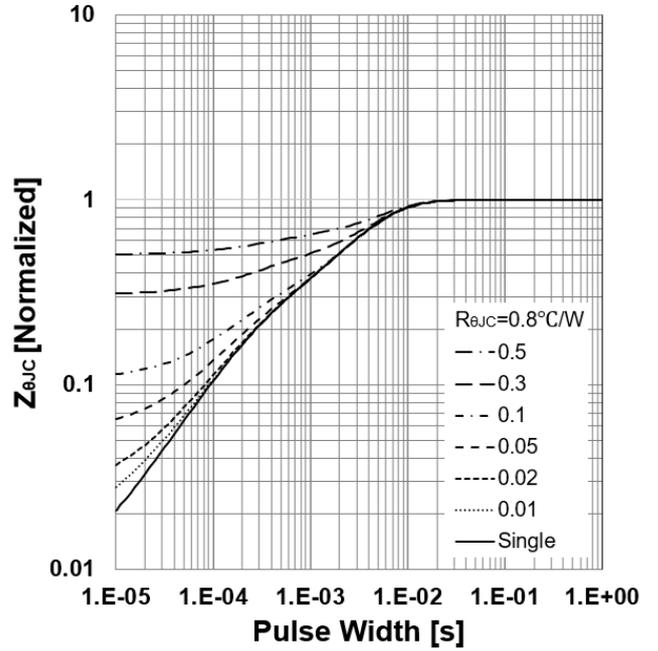


FIG.10 Normalized Transient Impedance

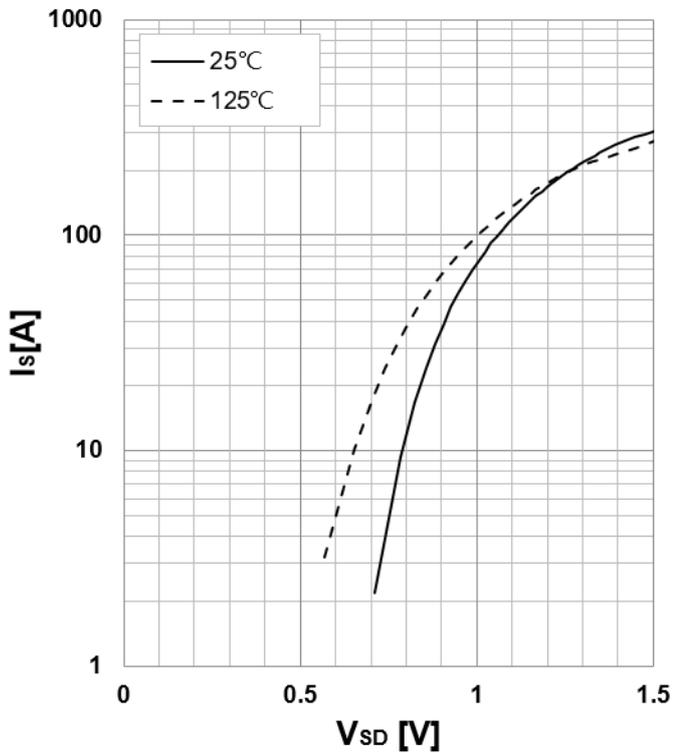
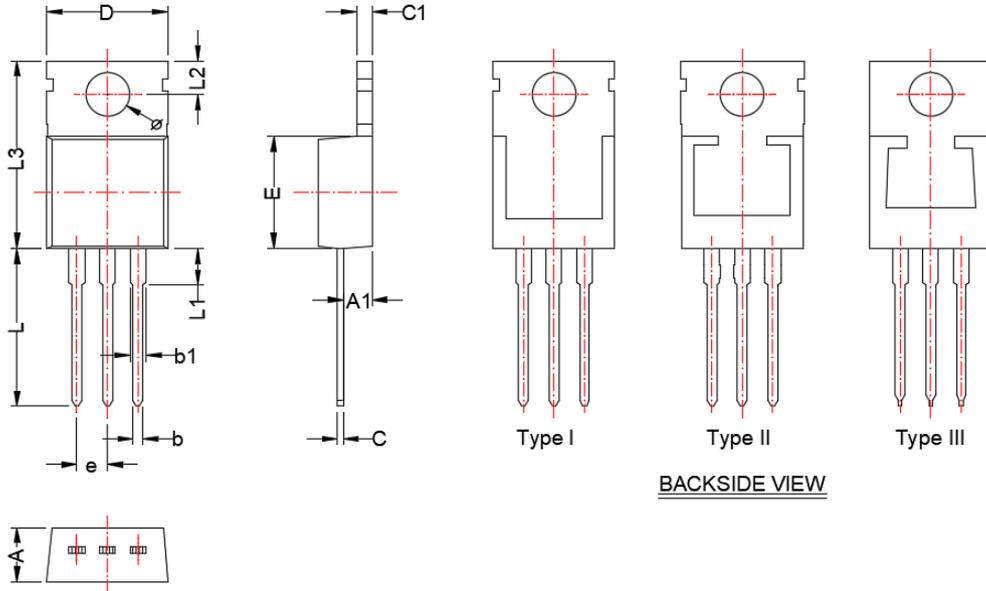


FIG.11 Body-Diode Characteristics

# TO-220-3L

## Package Dimension



Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
<b>A</b>	3.56	4.82	0.140	0.190
<b>A1</b>	2.03	2.92	0.080	0.115
<b>b</b>	0.38	1.14	0.015	0.045
<b>b1</b>	1.00	1.78	0.039	0.070
<b>c</b>	0.30	1.14	0.012	0.045
<b>c1</b>	0.51	1.50	0.020	0.059
<b>D</b>	9.50	10.67	0.374	0.420
<b>E</b>	8.38	9.42	0.330	0.371
<b>e</b>	2.54 BSC		0.100 BSC	
<b>L</b>	12.00	14.73	0.472	0.250
<b>L1</b>	---	7.00	---	0.250
<b>L2</b>	2.54	3.43	0.100	0.135
<b>L3</b>	14.22	16.51	0.560	0.650
<b>ø</b>	3.40	4.09	0.134	0.161

**NOTE:**  
Dimensions are exclusive of Burrs, Mold Flash and Tie Bar extrusions.

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